CLAIMS

What is claimed is:

1. A device enclosure comprising:
a thermo-siphon device embedded in an enclosure skin.

2. The device of claim 1, wherein the device is an electronic device.

3. The device of claim 2, wherein the device enclosure is a computer chassis.

4. The device of claim 1, wherein the device is a non-electronic device.

5. The device of claim 1, wherein the thermo-siphon device is a heat pipe.

6. The device of claim 1, wherein the thermo-siphon device is a strip of a high efficiency conduit material.

7. The device of claim 1, wherein the thermo-siphon device is an integral part of the skin.

8. The device of claim 7, wherein the thermo-siphon device is embedded in the skin during the manufacturing process of the skin.

9. The device of claim 1, wherein the skin is fabricated from a metallic material.

10. The device of claim 1, wherein the thermo-siphon device is embedded in a skin cavity.

11. The device of claim 10, wherein the cavity is created during a fabrication process of the skin.

12. The device of claim 1, wherein the skin partially encloses the thermo-siphon device.

13. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.

14. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.

15. The device of claim 1, wherein the thermo-siphon device is not an integral part of the skin.

16. The device of claim 15, wherein the thermo-siphon device can be inserted and removed from a skin cavity by accessing the interior of the enclosure.

17. The device of claim 1, wherein the thermo-siphon device is secured to a skin cavity through the means selected from the group consisting of a support provided by skin cavity walls, a thermal epoxy, and an interference fit with the skin cavity.

18. The device of claim 1, wherein a metallic plate interfaces a heat source with the thermo-siphon device.

19. A system comprising:

a housing including a thermo-siphon device embedded in a housing skin.

Cont Sub A1

20. The system of claim 19, wherein the thermo-siphon device is a heat pipe.

21. The system of claim 19, wherein the thermo-siphon device is a strip of high efficiency conduit material.

22. The system of claim 19, wherein the housing is a computer chassis.

23. The system of claim 19, wherein the thermo-siphon device is an integral part of the housing skin.

24. A computer chassis comprising:

a thermo-siphon device embedded in a computer chassis skin.

Cont Sub A1

25. The computer chassis of claim 24, wherein the thermo-siphon device is a heat pipe.

26. The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.

27. The computer chassis of claim 24, wherein the thermo-siphon device is an integral part of the skin.

28. The computer chassis of claim 27, wherein the thermosiphon device is embedded in the skin during the manufacturing process of the skin.